

Product/ Process Change (PCN) Notification

PCN Number: CO-16381	Contact: Elizabeth La Greca	
Date Issued: Mar 3 rd , 2017	Title: Director, Sales Operations	
PCN Effective Date: Jun 3 rd , 2017	Phone: 858-255-7839	
Product(s) Affected: PE4312 DIE	Email: PCN@psemi.com	
Sample Availability: Mar 3 rd , 2017		
Change Control Board Approval #: CO-16381		
Change Category:		
☐ Wafer Fabrication Process - Dual Source	Shipping/Labeling	
☐ Design/Mask Change	☐ Equipment	
☐ Singulation Process	☐ Material	
Assembly Process	Product Specification	
☐ Electrical Test	☐ Product End of Life	
☐ Manufacturing Site	Other - Ordering Code	
Purpose of Change:		
To enable MagnaChip and Lapis as dual source wafer fabrication sites		
Description of Change:		
MagnaChip closed their 150 mm wafer CMOS fab in South Korea at the end of 2015. To ensure there is no disruption to supply, we have been working to transfer products from MagnaChip fab to Lapis fab in Japan. Magnachip and Lapis are qualified Peregrine fabs. Lapis PE4312 DIE material has been qualified with no change to form, fit, function or reliability. Beginning Jun 3rd, 2017, the PE4312 DIE shipped to customers will be supplied from either MagnaChip or Lapis wafers.		
Ordering codes: (Original) MagnaChip part number: PE4312MLBA-E (New) Lapis part number: PE4312C-E		
For more information, please contact PCN@psemi.com.		

^{*}Customer Acknowledgement is based upon JEDEC Standard, JESD46D. Form # DOC-00558 Rev 2 If there is a difference between JEDEC and specific customer requirements, customer requirements take precedence.



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Customer Acknowledgement of Receipt*:		
Change Denied	Name:	
(Include explanation in		
comments section below)	Title:	
Change Approved	Company:	
	Date:	
	Signature:	
Customer Comments:		

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